

Environmental Protection Agency

§ 413.64

toxic organic management plan approved by the control authority.

(Secs. 301, 304, 306, 307, 308, and 501 of the Clean Water Act (the Federal Water Pollution Control Act Amendments of 1972, 33 U.S.C. 1251 *et. seq.*, as amended by the Clean Water Act of 1977, Pub. L. 95-217))

[46 FR 9467, Jan. 28, 1981, as amended at 48 FR 32484, July 15, 1983; 48 FR 43681, Sept. 26, 1983]

Subpart F—Chemical Etching and Milling Subcategory

§ 413.60 Applicability: Description of the chemical etching and milling subcategory.

The provisions of this subpart apply to discharges of process wastewaters resulting from the chemical milling or etching of ferrous or nonferrous materials.

§ 413.61 Specialized definitions.

For the purpose of this subpart:

(a) The term *sq m* ("sq. ft.") shall mean the area exposed to process chemicals expressed in square meters (square feet).

(b) The term *operation* shall mean any step in the chemical milling or etching processes in which metal is chemically or electrochemically removed from the work piece and which is followed by a rinse; this includes related metal cleaning operations which preceded chemical milling or etching, when each operation is followed by a rinse.

§§ 413.62–413.63 [Reserved]

§ 413.64 Pretreatment standards for existing sources.

Except as provided in 40 CFR 403.7 and 403.13, any existing source subject to this subpart which introduces pollutants into a publicly owned treatment works must comply with 40 CFR Part 403 and achieve the following pretreatment standards for existing sources (PSES):

(a) No User introducing wastewater pollutants into publicly owned treatment works under the provisions of

this subpart shall augment the use of process wastewater or otherwise dilute the wastewater as a partial or total substitute for adequate treatment to achieve compliance with this standard.

(b) For a source discharging less than 38,000 liters (10,000 gal.) per calendar day of electroplating process wastewater the following limitations shall apply:

SUBPART F—CHEMICAL ETCHING AND MILLING FACILITIES DISCHARGING LESS THAN 38,000 LITERS PER DAY PSES LIMITATIONS (MG/L)

Pollutant or pollutant property	Maximum for any 1 day	Average of daily values for 4 consecutive monitoring days shall not exceed
CN, A	5.0	2.7
Pb	0.6	0.4
Cd	1.2	0.7

(c) For plants discharging 38,000 liters (10,000 gal.) or more per calendar day of electroplating process wastewater the following limitations shall apply:

SUBPART F—CHEMICALS ETCHING AND MILLING FACILITIES DISCHARGING 38,000 LITERS OR MORE PER DAY PSES LIMITATIONS (MG/L)

Pollutant or pollutant property	Maximum for any 1 day	Average of daily values for 4 consecutive monitoring days shall not exceed
CN, T	1.9	1.0
Cu	4.5	2.7
Ni	4.1	2.6
Cr	7.0	4.0
Zn	4.2	2.6
Pb	0.6	0.4
Cd	1.2	0.7
Total metals	10.5	6.8

(d) Alternatively, the following mass-based standards are equivalent to and may apply in place of those limitations specified under paragraph (c) of this section upon prior agreement between a source subject to these standards and the publicly owned treatment works receiving such regulated wastes:

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SUBPART F—CHEMICAL ETCHING AND MILLING FACILITIES DISCHARGING 38,000 LITERS OR MORE PER DAY PSES LIMITATIONS (MG/SQ M-OPERATION)

Pollutant or pollutant property	Maximum for any 1 day	Average of daily values for 4 consecutive monitoring days shall not exceed
CN, T	74	39
Cu	176	105
Ni	160	100
Cr	273	156
Zn	164	102
Pb	23	16
Cd	47	29
Total metals	410	267

(e) For wastewater sources regulated under paragraph (c) of this section, the following optional control program may be elected by the source introducing treated process wastewater into a publicly owned treatment works with the concurrence of the control authority. These optional pollutant parameters are not eligible for allowance for removal achieved by the publicly owned treatment works under 40 CFR 403.7. In the absence of strong chelating agents, after reduction of hexavalent chromium wastes, and after neutralization using calcium oxide (or hydroxide) the following limitations shall apply:

SUBPART F—CHEMICAL ETCHING AND MILLING FACILITIES DISCHARGING 38,000 LITERS OR MORE PER DAY PSES LIMITATIONS (MG/L)

Pollutant or pollutant property	Maximum for any 1 day	Average of daily values for 4 consecutive monitoring days shall not exceed
CN, T	1.9	1.0
Pb	0.6	0.4
Cd	1.2	0.7
TSS	20.0	13.4
pH	(¹)	(¹)

¹ Within the range 7.5 to 10.0

(f) In addition to paragraphs (a) and (b) of this section, the following limitation shall apply for plants discharging less than 38,000 l (10,000 gal) per calendar day of electroplating process wastewater:

40 CFR Ch. I (7-1-00 Edition)

Pollutant or pollutant property	Maximum for any 1 day
	Milligrams per liter (mg/l)
TTO	4.57

(g) In addition to paragraphs (a), (c), (d), and (e) of this section, the following limitation shall apply for plants discharging 38,000 l (10,000 gal) or more per calendar day of electroplating process wastewater:

Pollutant or pollutant property	Maximum for any 1 day
	Milligrams per liter (mg/l)
TTO	2.13

(h) In addition to paragraphs (a), (b), (c), (d), (e), (f), and (g) of this section, the following shall apply: An existing source submitting a certification in lieu of monitoring pursuant to §413.03 of this regulation must implement the toxic organic management plan approved by the control authority.

(Secs. 301, 304, 306, 307, 308, and 501 of the Clean Water Act (the Federal Water Pollution Control Act Amendments of 1972, 33 U.S.C. 1251 *et. seq.*, as amended by the Clean Water Act of 1977, Pub. L. 95-217))

[46 FR 9467, Jan. 28, 1981, as amended at 48 FR 32484, July 15, 1983; 48 FR 43681, Sept. 26, 1983]

Subpart G—Electroless Plating Subcategory

§413.70 Applicability: Description of the electroless plating subcategory.

The provisions of this subpart apply to discharges resulting from the electroless plating of a metallic layer on a metallic or nonmetallic substrate.

§413.71 Specialized definitions.

For the purpose of this subpart:

(a) The term *sq m* ("sq. ft.") shall mean the area plated expressed in square meters (square feet).

(b) The term *electroless plating* shall mean the deposition of conductive material from an autocatalytic plating solution without application of electrical current.